

5.0mm x 5.0mm SURFACE MOUNT LED LAMP

Part Number: AAAF5051XQR412ZXS-N1

Neutral White



ATTENTION

OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- White SMD package, silicone resin.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

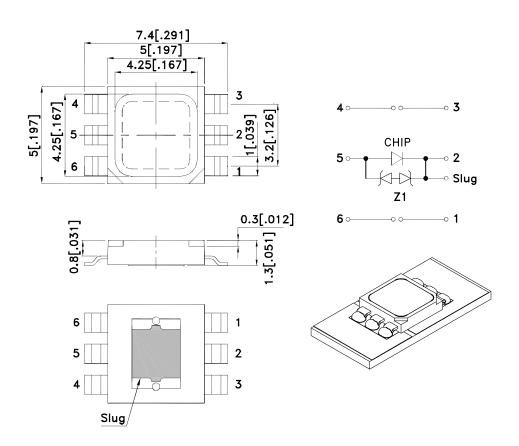
The source color devices are made with InGaN Vertical Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15[±0.006]unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.



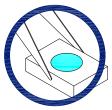
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Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

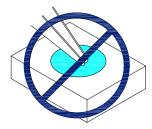
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

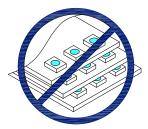


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

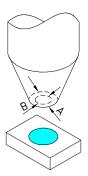




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide

Part No.	Dice	Base Order Codes Luminous Flux (Im) @ 350mA [1]		x (lm)	Typical Lumi- nous Flux (lm) [1]	
			Code.	Min.	Max.	Тур.
			B11	60	70	
AAAF5051XQR412ZXS-N1	Neutral White (InGaN)	WATER CLEAR	B12	70	80	70
AAAFSUSTAQR412ZAS-NT	Neutral Wille (IIIGall)	WATER CLEAR	B13	80	90	70
			B14	90	100	

Note

Absolute Maximum Ratings at TA=25°C

Absolute Maximum Natings at TA-23 C								
Items	Symbol	Neutral White	Unit					
DC Forward Current	lF	350	mA					
Peak Forward Current [1]	IFP	500	mA					
Reverse Voltage	VR	5	V					
Power Dissipation	PD	1400	mW					
Operating Temperature	Topr	-40 To +100	°C					
Storage Temperature	Tstg	-40 To +110	°C					
Junction Temperature	TJ	130	°C					

Note

Electrical / Optical Characteristics at Ta=25°C

Characteristics	Color	Symbol	Conditions	Unit	Minimum	Typical	Maximum
Forward Voltage [1]	Neutral White	VF	IF=350mA	V	3.0	3.5	4.0
Reverse Voltage	Neutral White	VR	V _R = 5V	uA			10
Color Reproduction Index	Neutral White	CRI	IF=350mA	-		65	
CCT Range	Neutral White	ССТ	IF=350mA	К	3710	4000	4260
Junction/ambient	Neutral White	Rth j-a	Ir=350mA	°C/W		70	
Junction/solder point	Neutral White	Rth j-s	IF=350mA	°C/W		30	
50% Power Angle	Neutral White	θ	IF=350mA	degrees		120	

Note:

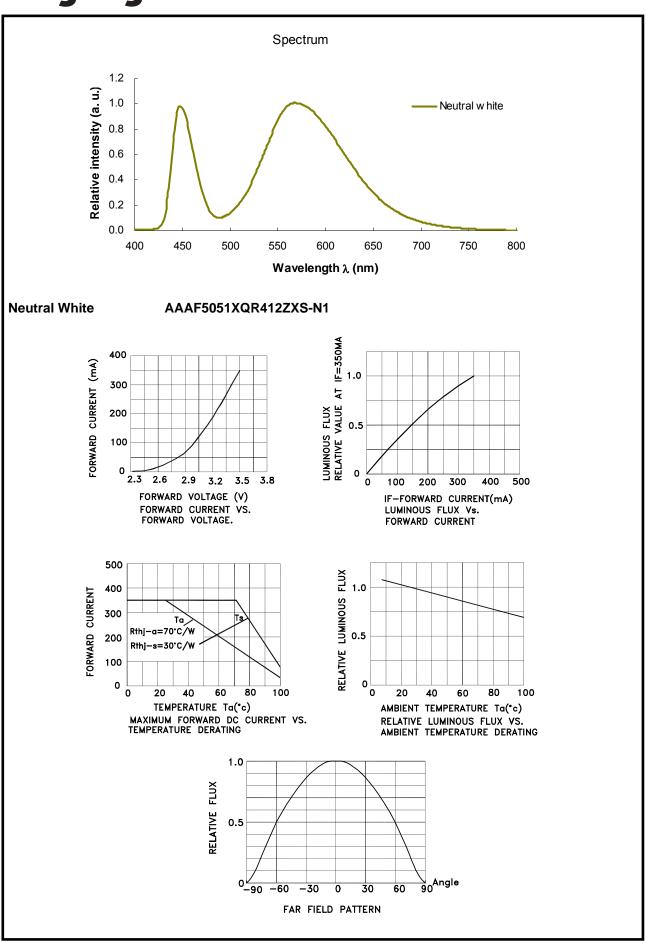
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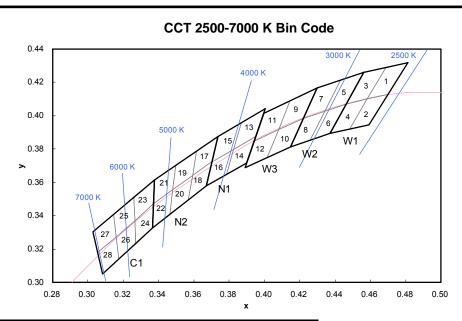
^{1.} Minimum luminous flux performance guaranteed within published operating conditions. Kingbright maintains tolerance of +/-15% on flux.

^{1.} Pulse Width=10 msec,Duty Cycle=10%

^{1.} Forward Voltage: +/-0.1V.



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Color	Group	Chromaticity Regions	CCT (K)			
Coloi	Group	Chilomaticity Regions	Min.	Тур.	Max.	
	W1	1, 2, 3, 4	2580	2700	2870	
Warm White	W2	5, 6, 7, 8	2870	3000	3220	
	W3	9, 10, 11, 12	3220	3500	3710	
Neutral White	N1	13, 14, 15, 16	3710	4000	4260	
ineutral write	N2	17, 18, 19, 20, 21, 22	4260	4700	5310	
Cool White	C1	23, 24, 25, 26, 27, 28	5310	6000	7040	

Notes:

Shipment may contain more than one chromaticity regions. Orders for single chromaticity region are generally not accepted.

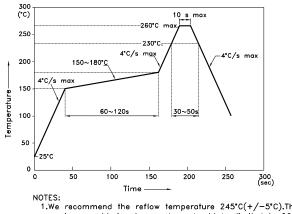
Measurement tolerance of the chromaticity coordinates is ±0.01.

		v .	,,	,,							
	Х	у		Х	у		Х	у		Х	у
1	0.4582	0.4099	8	0.4147	0.3814	15	0.3702	0.3722	22	0.3481	0.3557
	0.4687	0.4289		0.4221	0.3984		0.3736	0.3874		0.3370	0.3472
	0.4813	0.4319		0.4342	0.4028	15	0.3869	0.3958		0.3364	0.3328
	0.4700	0.4126		0.4259	0.3853		0.3825	0.3798		0.3466	0.3411
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578	23	0.3376	0.3616
2	0.4582	0.4099	9	0.4146	0.4089	16	0.3702	0.3722		0.3260	0.3512
_	0.4700	0.4126		0.4299	0.4165	10	0.3825	0.3798	20	0.3265	0.3371
	0.4593	0.3944		0.4221	0.3984		0.3783	0.3646		0.3370	0.3472
	0.4465	0.4071		0.4017	0.3751	17	0.3736	0.3874	24	0.3370	0.3472
3	0.4562	0.4260	10	0.4080	0.3916		0.3616	0.3788		0.3265	0.3371
	0.4687	0.4289		0.4221	0.3984		0.3592	0.3641		0.3270	0.3230
	0.4582	0.4099		0.4147	0.3814		0.3703	0.3726		0.3364	0.3328
	0.4373	0.3893	11	0.3941	0.3848	18	0.3703	0.3726	25	0.3260	0.3512
4	0.4465	0.4071		0.3996	0.4015		0.3592	0.3641		0.3144	0.3408
7	0.4582	0.4099		0.4146	0.4089		0.3568	0.3495		0.3160	0.3274
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3265	0.3371
	0.4342	0.4028		0.3889	0.3690		0.3616	0.3788	26	0.3265	0.3371
5	0.4430	0.4212	12	0.3941	0.3848	19	0.3496	0.3702		0.3160	0.3274
5	0.4562	0.4260	12	0.4080	0.3916	19	0.3481	0.3557		0.3175	0.3139
	0.4465	0.4071		0.4017	0.3751		0.3592	0.3641		0.3270	0.3230
	0.4259	0.3853		0.3825	0.3798		0.3592	0.3641	27	0.3144	0.3408
6	0.4342	0.4028	13	0.3869	0.3958	20	0.3481	0.3557		0.3028	0.3304
0	0.4465	0.4071	13	0.4006	0.4044	20	0.3466	0.3411		0.3055	0.3177
	0.4373	0.3893		0.3950	0.3875		0.3568	0.3495		0.3160	0.3274
	0.4221	0.3984	14	0.3783	0.3646	21	0.3496	0.3702	28	0.3160	0.3274
7	0.4299	0.4165		0.3825	0.3798		0.3376	0.3616		0.3055	0.3177
	0.4430	0.4212		0.3950	0.3875		0.3370	0.3472		0.3081	0.3049
	0.4342	0.4028		0.3898	0.3716		0.3481	0.3557		0.3175	0.3139

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.





- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.

 3.Number of reflow process shall be 2 times or less.

Heat Generation:

1.Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board ,as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

2.Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Permissible Forward current vs. Ambient temperature on CHARACTERISTICS in this specification. Please also take measures to remove heat from the area near the LED to improve the operational characteristics on the LED.

3.The equation ① indicates correlation between T_j and T_a and the equation ② indicates correlation between T_j and T_s

 $T_j = Ta + Rth_j - a *W \dots 1$

Tj = Ts + Rthj-s *W 2

Tj = dice junction temperature: $^{\circ}$ C

Ta = ambient temperature: ℃

Ts = solder point temperature: ℃

Rthj-s = heat resistance from dice junction temperature to Ts measuring point : °C /W

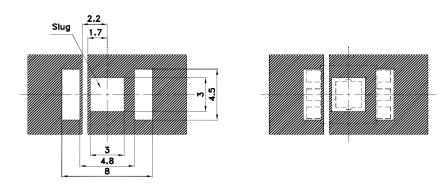
W = inputting power (IFx VF) : W

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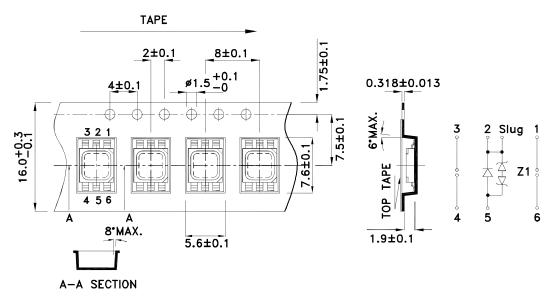
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Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

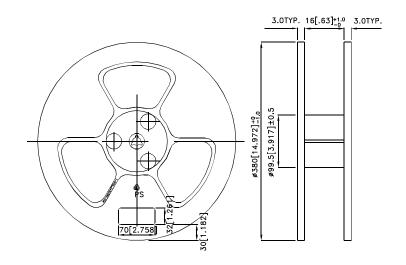


Tape Specifications

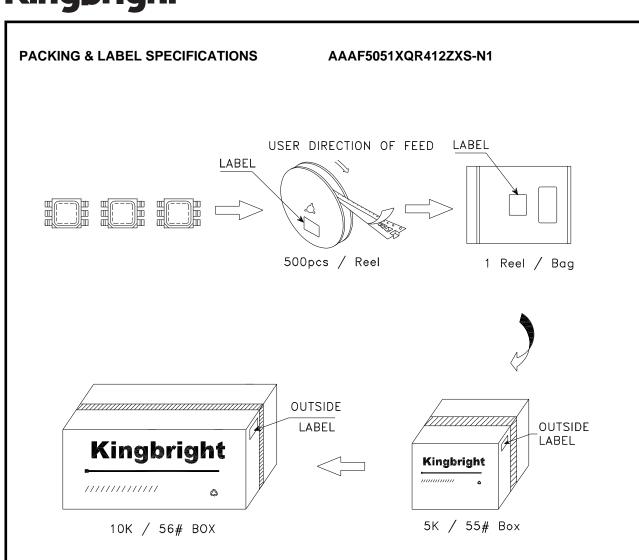
(Units: mm)



Reel Dimension



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